

In the claims:

Please amend the claims as follows:

1. (Currently Amended) A semiconductor device comprising:  
a supporting substrate made of insulating material;  
a conductive pattern provided on a surface of the supporting substrate;  
an external connecting terminal provided on a back surface of the supporting substrate  
and electrically connected to the conductive patterns;  
a circuit element provided on the conductive pattern; and  
a transparent glass plate that covers the circuit element and that forms a hollow airtight  
portion between the supporting substrate and the transparent glass plate.
2. (Canceled)
3. (Original) A semiconductor device according to claim 1, wherein the supporting  
substrate includes a flat supporting portion and a column portion, and the conductive patterns are  
provided on the flat supporting portion.
4. (Currently Amended) A semiconductor device according to claim 1, wherein the  
transparent glass plate is adhered onto the column portion.
5. (Original) A semiconductor device according to claim 1, wherein a via hole is provided  
in the supporting substrate, and the circuit element and the external connecting terminals are  
electrically connected through the via hole.
6. (Original) A semiconductor device according to claim 1, wherein the circuit element  
is formed of one of a semiconductor element and a fuse element.
7. (Original) A semiconductor device according to claim 6, wherein the fuse element is  
formed of a bonding wire.

Applicant : Haruo Hyodo et al.  
Serial No. : 09/963,839  
Filed : September 26, 2001  
Page : 3 of 5

Attorney's Docket No.: 10417-100001 / F51-  
136641M/TOM

Claims 8 – 11 (Withdrawn)